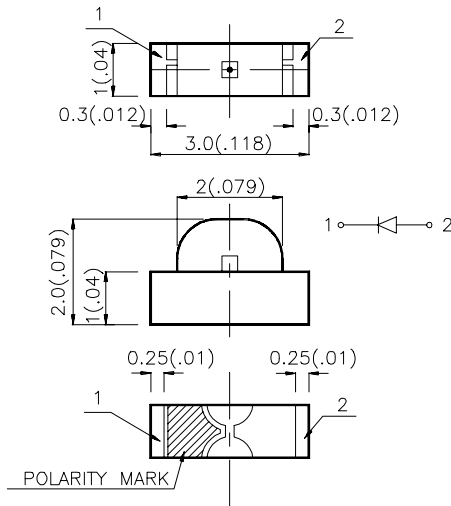


Package Dimensions

3.0x1.0mm SMD CHIP LED LAMP

EPA3010SF4C



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.15(0.006")$ unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Features

1. 3.0mmx1.0mm SMT LED, 2.0mm THICKNESS.
2. LOW POWER CONSUMPTION.
3. WIDE VIEWING ANGLE.
4. IDEAL FOR BACKLIGHT AND INDICATOR.
5. VARIOUS COLORS AND LENS TYPES AVAILABLE.

Description

SF4 Made with Gallium Aluminum Arsenide Infrared Emitting diodes.

Selection Guide

Part No.	Emitting Color +Material	P(nm)	Lens Type	I _v (mcd) @ 20 mA		Viewing Angle
				Min.	Typ.	
EPA3010SF4C	GaAlAs	880	WATER CLEAR	0.5	1.0	2 θ 1/2

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

DATA NO :EA0225

REV NO :V1

DATE :SEP/03/2001

Electrical / Optical Characteristics at T_A=25°C

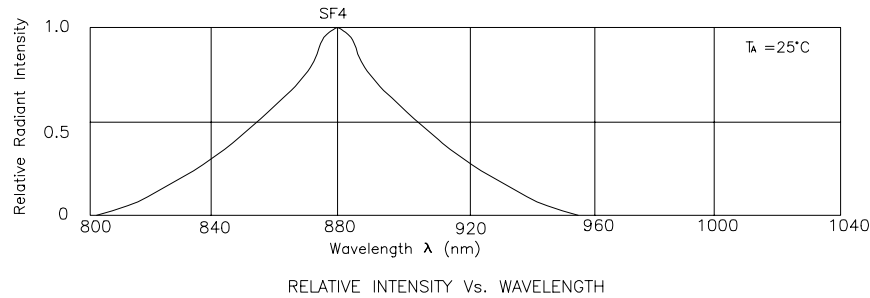
Item	P/N	Symbol	Typ.	Max.	Unit	Condition
Forward Voltage	SF4	V _F	1.3	1.6	V	I _F =20mA
Reverse Current	SF4	I _R	-	10	uA	V _R =5V
Junction Capacitance	SF4	C	90	-	pF	V=0 f=1MHz
Peak Spectral Wavelength	SF4	λ _P	880	-	nm	I _F =20mA
Spectral Bandwidth	SF4	Δλ	50	-	nm	I _F =20mA

Absolute Maximum Ratings at T_A=25°C

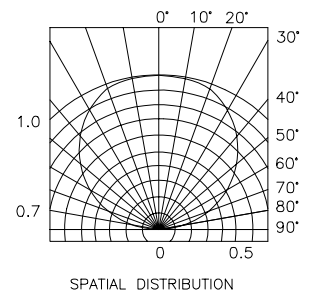
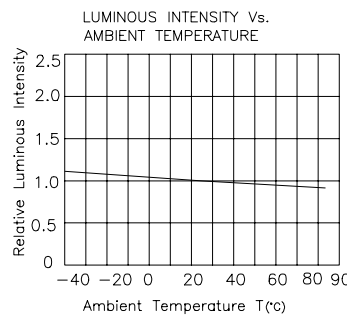
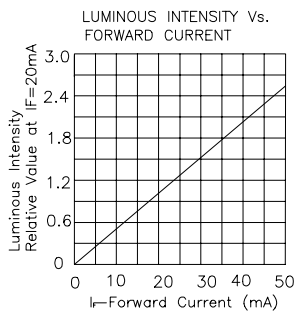
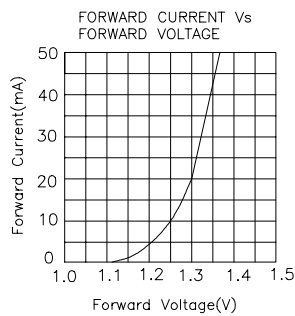
Item	Symbol	Maximum Rating	Units
Power Dissipation	P _d	100	mW
Forward Current	I _F	50	mA
Peak Forward Current	I _P	1.0	A
Reverse Voltage	V _R	5	V
Operating Temperature	T _{opr}	-40~ +85	°C
Storage Temperature	T _{stg}	-40~ +85	°C

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

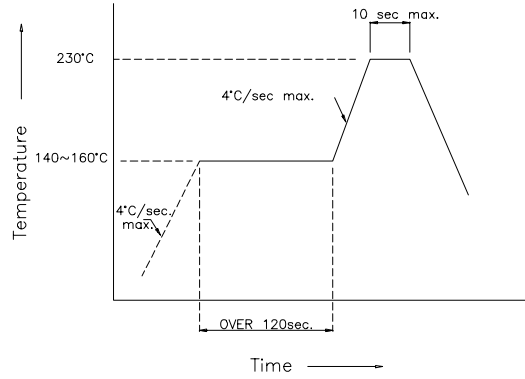


EPA3010SF4C

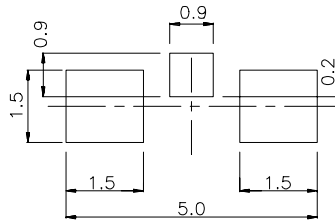


EPA3010SF4C SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



**EPA3010SF4C Recommended Soldering Pattern
(Units : mm)**



**EPA3010SF4C Tape Specifications
(Units : mm)**

PACKAGE : 2000PCS / REEL

